



UMB05F~UMB10F

Ultra Miniature Glass Passivated Single-Phase Surface Mount Flat Bridge Rectifier

Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC



SOF2-4

Mechanical Data

- **Case:** SOF2-4 Molded plastic over glass passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Polarity symbols marked on body

Major Ratings and Characteristics

$I_{F(AV)}$	0.5 A, 0.8 A
V_{RRM}	50V to 1000V
I_{FSM}	20 A
I_R	5.0 μA
V_F	1.1 V
T_j max.	150 °C

Maximum Ratings & Thermal Characteristics

(T_A = 25 °C unless otherwise noted)

Items	Symbol	UMB 05F	UMB 1F	UMB 2F	UMB 4F	UMB 6F	UMB 8F	UMB 10F	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _A =30°C -on glass-epoxy P.C.B. ⁽¹⁾ -on aluminum substrate ⁽²⁾	$I_{F(AV)}$				0.5 0.8				A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}				20				A
Thermal resistance from junction to ambient per leg	$R_{\theta JA}^{(1)}$ $R_{\theta JA}^{(2)}$			100 80					°C/W
Thermal resistance from junction to lead per leg ⁽¹⁾	$R_{\theta JL}$			30					°C/W
Operating junction and storage temperature range	T_j, T_{STG}			-55 to +150					°C

Note 1: On glass epoxy P.C.B. mounted on 0.06×0.04" (1.5×1.1mm) pads

Note 2: On aluminum substrate P.C.B. with an area of 0.8×0.8" (20×20mm) mounted on 0.06×0.04" (1.5×1.1mm) solder pad

Electrical Characteristics

(T_A = 25 °C unless otherwise noted)

Items	Test conditions		Symbol	Min	Type	Max	UNIT
Instantaneous forward voltage per leg	$I_F=0.4A^{(3)}$		V_F	-	0.96	1.10	V
Reverse current per leg	$V_R=V_{DC}$	$T_j=25^\circ C$ $T_j=125^\circ C$	I_R	-	-	5 100	μ A

Note 3: Pulse test:300μs pulse width, 1% duty cycle.



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Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

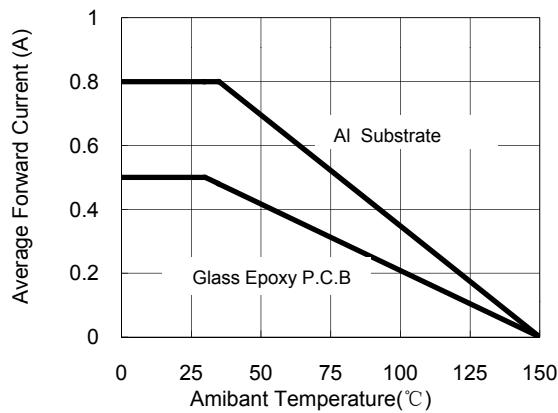


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

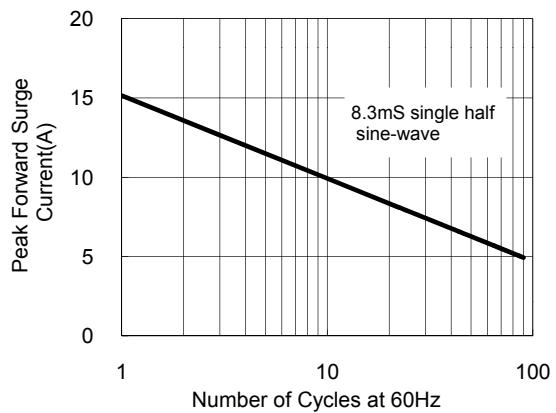


Fig.3 Typical Instantaneous Forward Characteristics

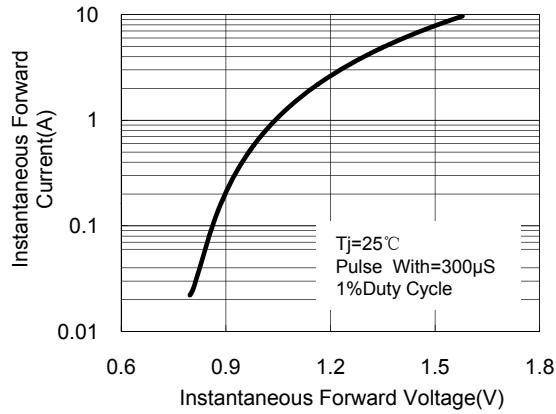
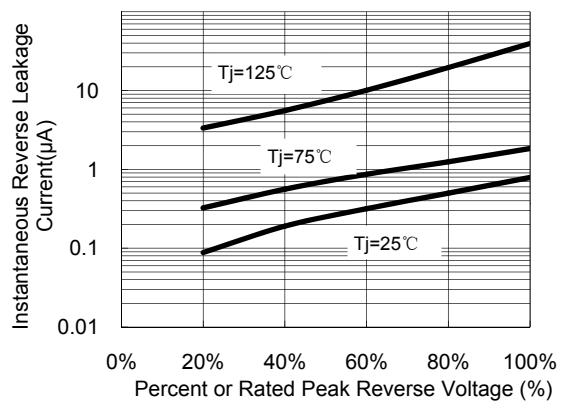


Fig.4 Typical Reverse Leakage Characteristics

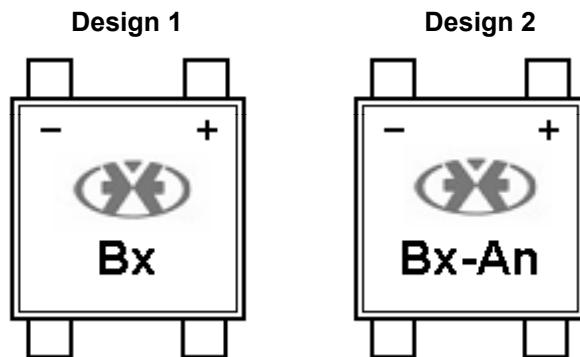




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Marking



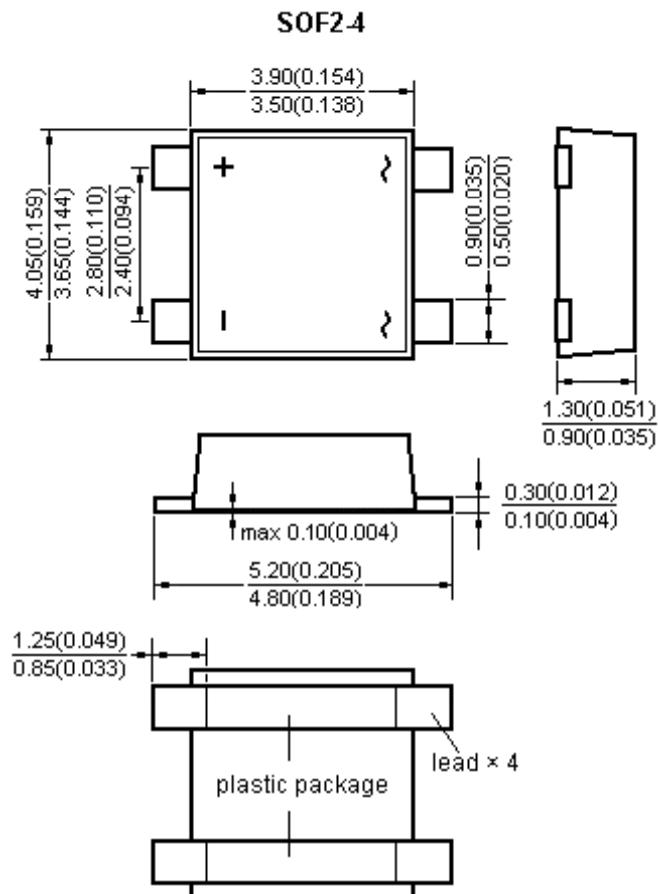
Annotation of Marking Code:

Device Type	Device Marking
UMB05F	B1
UMB1F	B2
UMB2F	B3
UMB4F	B4
UMB6F	B5
UMB8F	B6
UMB10F	B7

Marking meaning

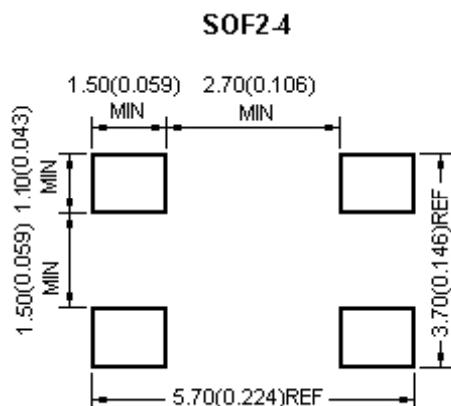
- = Trademark
- Bx = Marking Code, x = 1,2,3, … , 7. See the table at the right .
- An = Suppliers' Code. It's default as a general rule,like Design 1.

Package Outline



Dimensions in millimeters and (inches)

Soldering Pad



Dimensions in millimeters and (inches)